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Vishay Semiconductors

## High Performance Schottky Rectifier, 2 x 20 A

# Base common cathode 02 02

Anode cathode Anode

VS-43CTQ...SPbF

Common

VS-43CTQ...-1PbF

Anode

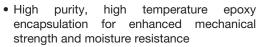
Common 0 3

cathode Anode

PRODUCT SUMMARY					
Package	TO-263AB (D <sup>2</sup> PAK), TO-262AA				
I <sub>F(AV)</sub>	2 x 20 A				
V <sub>R</sub>	80 V, 100 V				
V <sub>F</sub> at I <sub>F</sub>	0.67 V				
I <sub>RM</sub> max.	11 mA at 125 °C				
T <sub>J</sub> max.	175 °C				
Diode variation	Common cathode				
E <sub>AS</sub>	7.50 mJ				

#### **FEATURES**

- 175 °C T<sub>J</sub> operation
- Center tap configuration
- Low forward voltage drop





- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **DESCRIPTION**

This center tap Schottky rectifier series has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS						
SYMBOL	CHARACTERISTICS	VALUES	UNITS			
I <sub>F(AV)</sub>	Rectangular waveform	40	A			
V <sub>RRM</sub>		80/100	V			
I <sub>FSM</sub>	t <sub>p</sub> = 5 µs sine	850	A			
V <sub>F</sub>	20 A <sub>pk</sub> , T <sub>J</sub> = 125 °C (per leg)	0.67	V			
TJ	Range	-55 to +175	°C			

VOLTAGE RATINGS						
PARAMETER	SYMBOL	VS-43CTQ080SPbF VS-43CTQ080-1PbF	VS-43CTQ100SPbF VS-43CTQ100-1PbF	UNITS		
Maximum DC reverse voltage	V <sub>R</sub>	80	100	V		
Maximum working peak reverse voltage	$V_{RWM}$	60	100	V		

ABSOLUTE MAXIMUM RATINGS						
PARAMETER		SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average	per leg				20	
forward current See fig. 5	per device	I <sub>F(AV)</sub>	50 % duty cycle at T <sub>C</sub> = 135 °C, rectangular waveform		40	A
Maximum peak one cycle non-repetitive			5 μs sine or 3 μs rect. pulse Following any rated load		850	^
surge current per leg See fig. 7		I <sub>FSM</sub>	10 ms sine or 6 ms rect. pulse	condition and with rated V <sub>RRM</sub> applied	275	
Non-repetitive avalanche ener	gy per leg	E <sub>AS</sub>	$T_J = 25  ^{\circ}\text{C},  I_{AS} = 0.50  \text{A},  L = 60$	mH	7.50	mJ
Repetitive avalanche current p	per leg	I <sub>AR</sub>	Current decaying linearly to zero in 1 $\mu$ s  Frequency limited by T <sub>J</sub> maximum V <sub>A</sub> = 1.5 x V <sub>R</sub> typical		0.50	А

Revision: 15-Aug-15 1 Document Number: 94224



# VS-43CTQ...SPbF, VS-43CTQ...-1PbF Series

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ELECTRICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CO	TEST CONDITIONS			
		20 A	T <sub>.1</sub> = 25 °C	0.81		
Maximum forward voltage drop per leg	V <sub>FM</sub> <sup>(1)</sup>	40 A	1j=25 C	0.98	V	
See fig. 1	VFM (1)	20 A	T 105 °C	0.67		
		40 A	T <sub>J</sub> = 125 °C	0.81		
Maximum reverse leakage current per leg	I <sub>RM</sub> <sup>(1)</sup>	T <sub>J</sub> = 25 °C	V <sub>R</sub> = Rated V <sub>R</sub>	1	mA	
See fig. 2		T <sub>J</sub> = 125 °C		11		
Threshold voltage	V <sub>F(TO)</sub>	T T manyimuma		0.71	V	
Forward slope resistance	r <sub>t</sub>	$T_J = T_J$ maximum		0.43	mΩ	
Maximum junction capacitance per leg	C <sub>T</sub>	V <sub>R</sub> = 5 V <sub>DC</sub> (test signal rang	ge 100 kHz to 1 MHz), 25 °C	1480	pF	
Typical series inductance per leg	L <sub>S</sub>	Measured lead to lead 5 m	8.0	nH		
Maximum voltage rate of change	dV/dt	Rated V <sub>R</sub>		10 000	V/µs	

#### Note

 $^{(1)}\,$  Pulse width < 300  $\mu s,$  duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum junction and storage temperature range	<b>)</b>	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +175	°C	
Maximum thermal resistance, junction to case per leg		D	DC encystics	2.0		
Maximum thermal resistance, junction to case per package		HthJC	R <sub>thJC</sub> DC operation		°C/W	
Typical thermal resistance, case to heatsink		R <sub>thCS</sub>	Mounting surface, smooth and greased	0.50		
Approximate weight				2	g	
Approximate weight				0.07	OZ.	
Mounting torque	minimum			6 (5)	kgf · cm	
Mounting torque -	maximum			12 (10)	(lbf $\cdot$ in)	
			O I TO 0001D (D2D110	43CTC	Q080S	
Marking device			Case style TO-263AB (D <sup>2</sup> PAK)	43CT0	Q100S	
			Coop at the TO 2624A	43CTC	43CTQ080-1	
		Case style TO-262AA		43CTC	43CTQ100-1	

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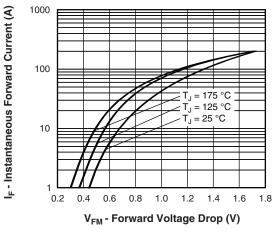


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

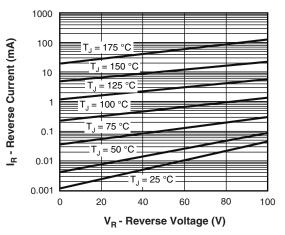


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

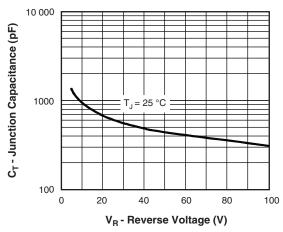


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

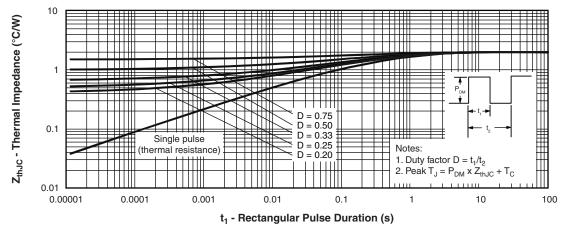


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics (Per Leg)





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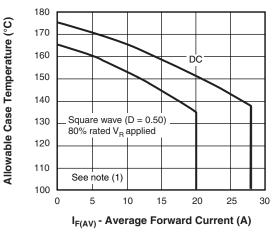


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current (Per Leg)

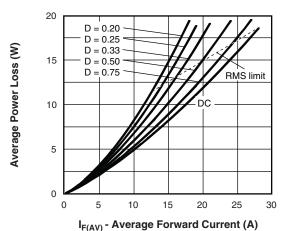


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

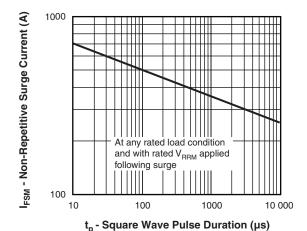


Fig. 7 - Maximum Non-Repetitive Surge Current (Per Leg)

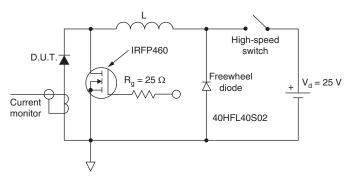


Fig. 8 - Unclamped Inductive Test Circuit

## Note

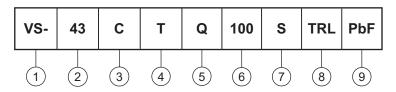
(1) Formula used:  $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$ ;  $Pd = Forward power loss = I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);  $Pd_{REV} = Inverse power loss = V_{R1} \times I_R$  (1 - D);  $I_R$  at  $V_{R1} = 10$  V

## VS-43CTQ...SPbF, VS-43CTQ...-1PbF Series

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## **ORDERING INFORMATION TABLE**

## **Device code**



1 - Vishay Semiconductors product

Current rating (40 A)

Circuit configuration: C = common cathode

4 - T = TO-220

5 - Schottky "Q" series

6 - Voltage ratings - 080 = 80 V 100 = 100 V

7 - • S = D<sup>2</sup>PAK

• -1 = TO-262

None = tube (50 pieces)

• TRL = tape and reel (left oriented - for D<sup>2</sup>PAK only)

• TRR = tape and reel (right oriented - for D<sup>2</sup>PAK only)

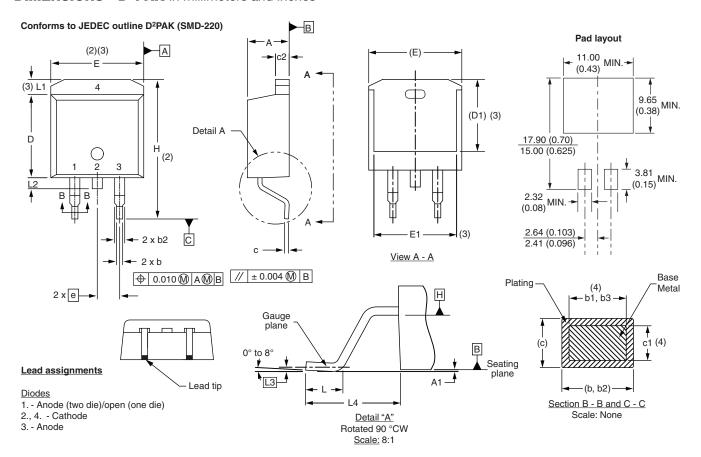
9 - PbF = lead (Pb)-free

LINKS TO RELATED DOCUMENTS						
Dimensions <u>www.vishay.com/doc?95014</u>						
Part marking information	www.vishay.com/doc?95008					
Packaging information	www.vishay.com/doc?95032					
SPICE model	www.vishay.com/doc?95065					

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## **D**<sup>2</sup>**PAK**, **TO**-262

## **DIMENSIONS - D<sup>2</sup>PAK** in millimeters and inches



SYMBOL	MILLIN	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	NOTES	
А	4.06	4.83	0.160	0.190		
A1	0.00	0.254	0.000	0.010		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
С	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
Е	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.100 BSC		
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010	BSC	
L4	4.78	5.28	0.188	0.208	

#### Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- $^{(3)}$  Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch

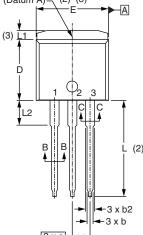
(7) Outline conforms to JEDEC outline TO-263AB

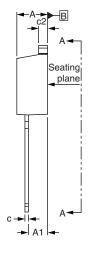
Document Number: 95014 Revision: 31-Mar-09

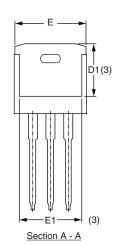


## **DIMENSIONS - TO-262** in millimeters and inches

# Modified JEDEC outline TO-262 (Datum A) - (2) (3)







**⊕** 0.010 **M** A **M** B

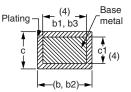
#### Lead assignments



#### Diodes

1. - Anode (two die)/open (one die) 2., 4. - Cathode

3. - Anode



Section B - B and C - C Scale: None

CYMPOL	MILLIMETERS		INC	INCHES		
SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.06	4.83	0.160	0.190		
A1	2.03	3.02	0.080	0.119		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
С	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	
D1	6.86	8.00	0.270	0.315	3	
Е	9.65	10.67	0.380	0.420	2, 3	
E1	7.90	8.80	0.311	0.346	3	
е	2.54 BSC		0.100	) BSC		
L	13.46	14.10	0.530	0.555		
L1	-	1.65	-	0.065	3	
L2	3.56	3.71	0.140	0.146		

### **Notes**

- $^{(1)}$  Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches

(6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline



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